

■外形尺寸和印记

SOD-123FL

Outline Dimensions and Mark

Dimensions in millimeters

■特征

Features

- I_o 1.0A
- V_{RRM} 20V-100V
- 耐正向浪涌电流能力高
High surge current capability
- 封装：模压塑料
Cases: Molded plastic

■用途

Applications

- 整流用 Rectifier

■极限值（绝对最大额定值）

Limiting Values (Absolute Maximum Rating)

参数名称 Item	符号 Symbol	单位 Unit	测试条件 Test Conditions	S 12	S 13	S 14	S 15	S 16	S 19	S 110
反向重复峰值电压 Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	90	100
正向平均电流 Average Forward Current	$I_{F(AV)}$	A	正弦半波 60Hz,电阻负载,Ta=50℃ 60Hz Half-sine wave, Resistance load, Ta=50℃	1.0						
正向（不重复）浪涌电流 Surge(Non-repetitive)Forward Current	I_{FSM}	A	正弦半波 60Hz, 一个周期,Ta=25℃ 60Hz Half-sine wave ,1 cycle , Ta=25℃	30						
结温 Junction Temperature	T_J	℃		-55~+125						
储存温度 Storage Temperature	T_{STG}	℃		-55 ~ +150						

■电特性（Ta=25℃ 除非另有规定）

Electrical Characteristics (Ta=25℃ Unless otherwise specified)

参数名称 Item	符号 Symbol	单位 Unit	测试条件 Test Condition		S 12	S 13	S 14	S 15	S 16	S 19	S 110
正向峰值电压 Peak Forward Voltage	V _F	V	I _F =1.0A		0.55			0.70		0.85	
反向漏电流 Peak Reverse Current	I _{R1}	mA	V _{RM} =V _{RRM}	T _a =25℃	0.5						
	I _{R2}			T _a =100℃	10		5.0		2.0		
热阻(典型) Thermal Resistance(Typical)	R _{θJ-A}	℃/W	结和环境之间 Between junction and ambient		88 ¹⁾						
	R _{θJ-L}		结和终端之间 Between junction and terminal		28 ¹⁾						

备注：Notes:

¹⁾ 热阻从结到环境及从结到引线，在电路板的0.2" x 0.2" (5.0毫米 x 5.0毫米)铜垫片区
Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

■ 特性曲线（典型）

图1：正向电流降额曲线
FIG.1: FORWARD CURRENT DERATING CURVE

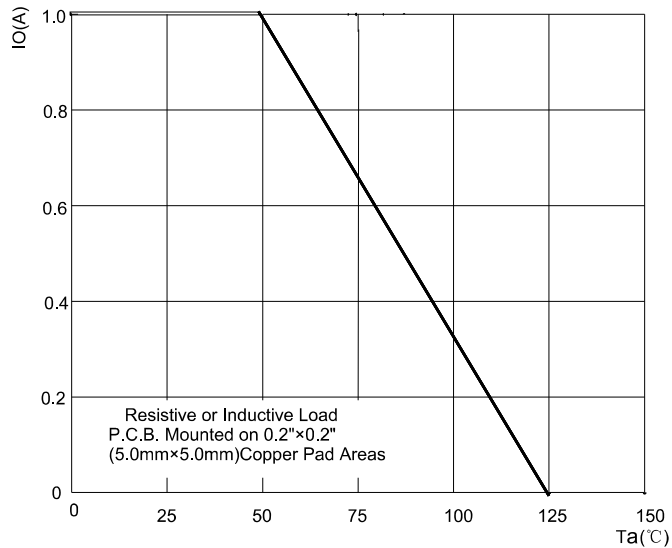


图2：最大正向浪涌冲击耐受力
FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

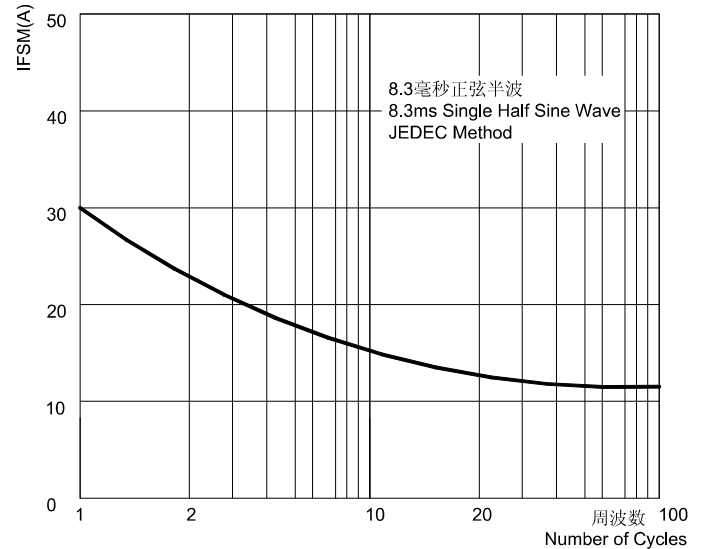


图3：典型正向特性曲线
FIG.3: TYPICAL FORWARD CHARACTERISTICS

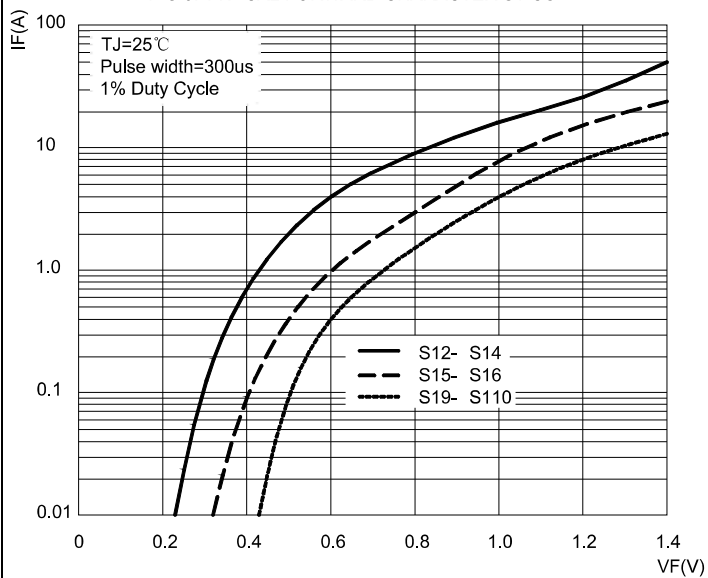


图4：典型反向特性曲线
FIG.4: TYPICAL REVERSE CHARACTERISTICS

